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# GLOBAL SEMICONDUCTOR MATERIALS MARKET 2024

## Overview

This one-of-its-kind report from Aranca provides the most comprehensive overview of the semiconductors eco-system and takes a deep-dive to analyze emerging market opportunities at each step of the value chain. Covering actionable intelligence on both the demand and supply side, this report is a must-read for every professional in the semiconductor domain.

## Key Highlights of the Report

**10+** Steps of the semi-conductor value chain analysed

**20+** Components with detailed analysis

**50+** Patent analysis - Materials and technology trends

**100+** Raw materials with insights on market opportunity

**300+** Suppliers and end-users profiled

## \*Key Components Included

- Wafer Carrying Components
- Wafer
- CVD precursors
- Photomasks
- Photoresist
- Etchant
- Etch Mask
- Dopants
- Polishing pads
- CMP Slurries
- Dicing tape
- Wire bonding
- Lead frame
- Semiconductor Packaging

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